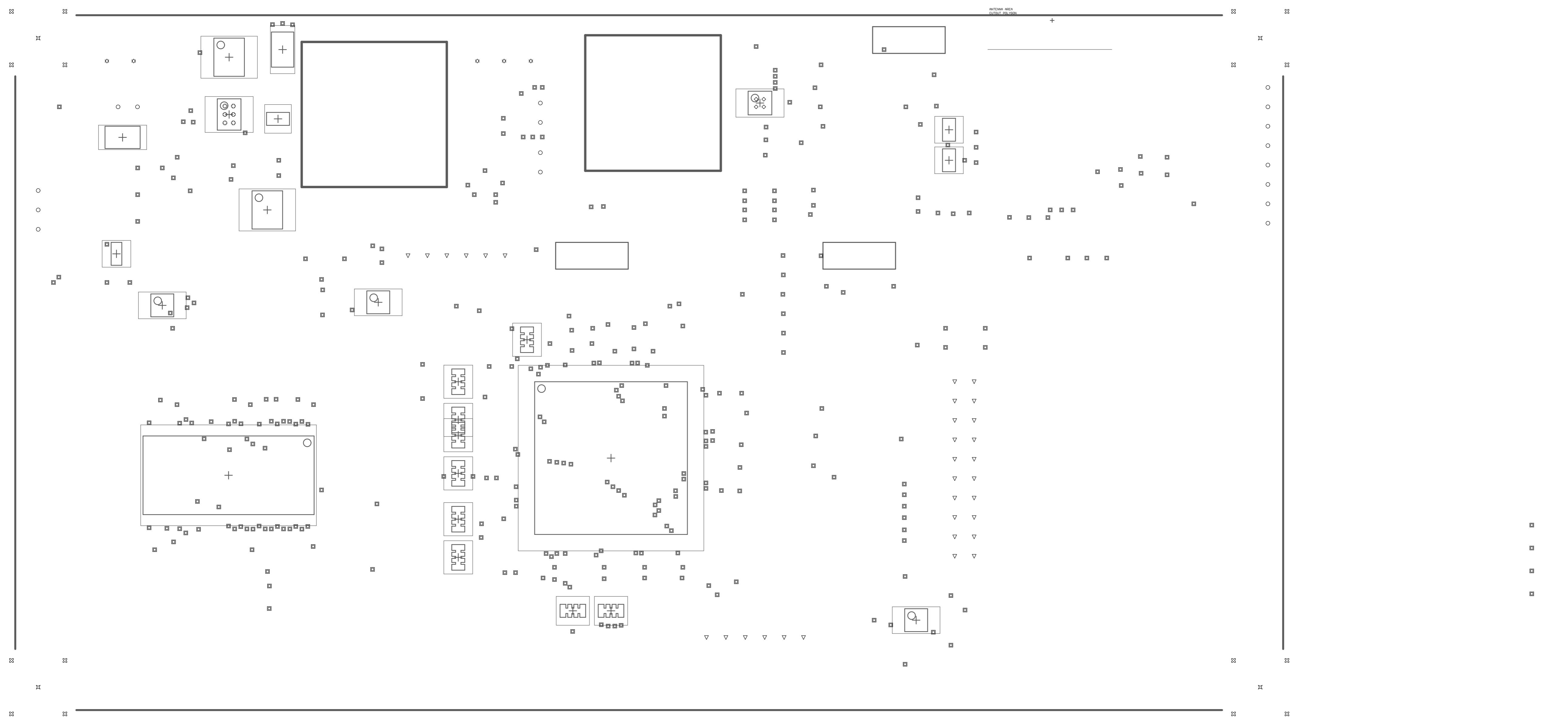
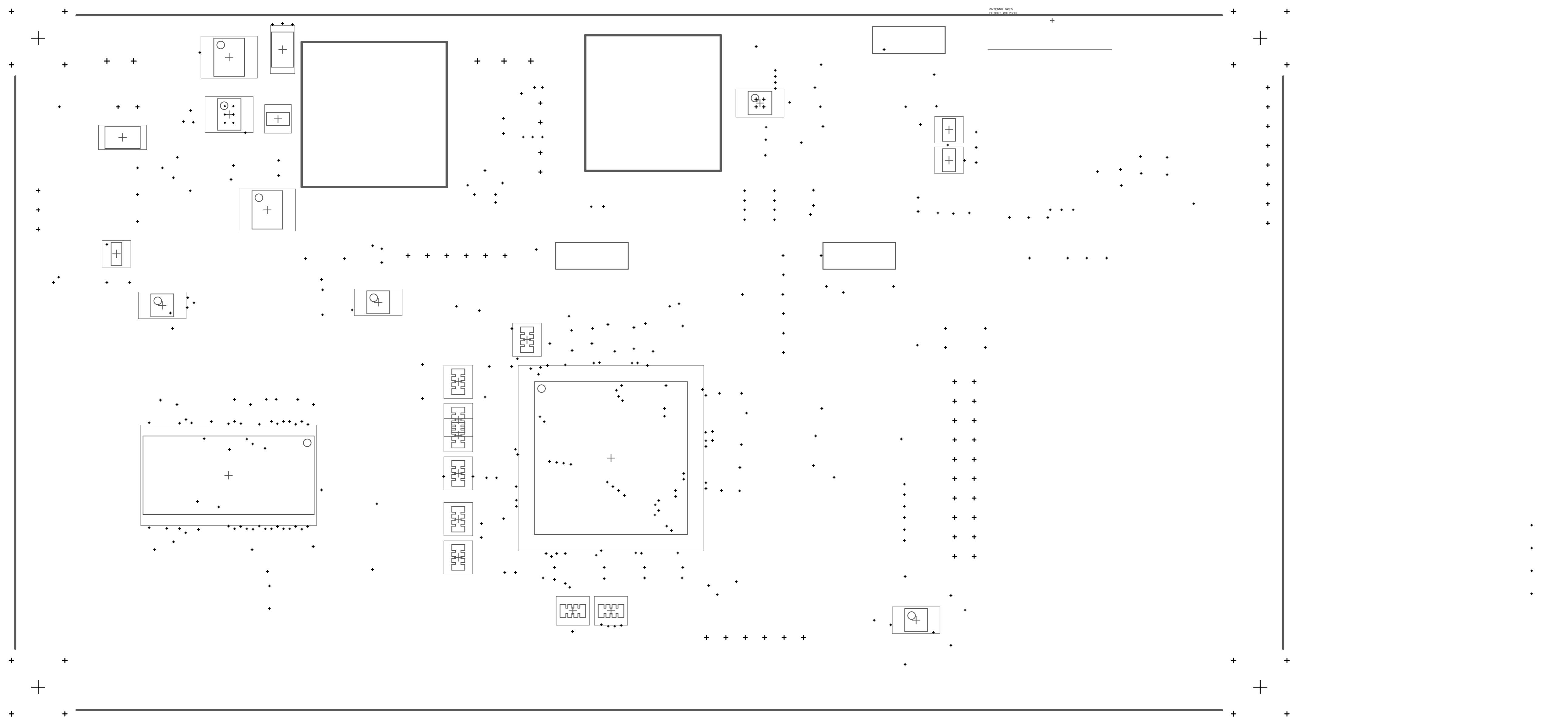
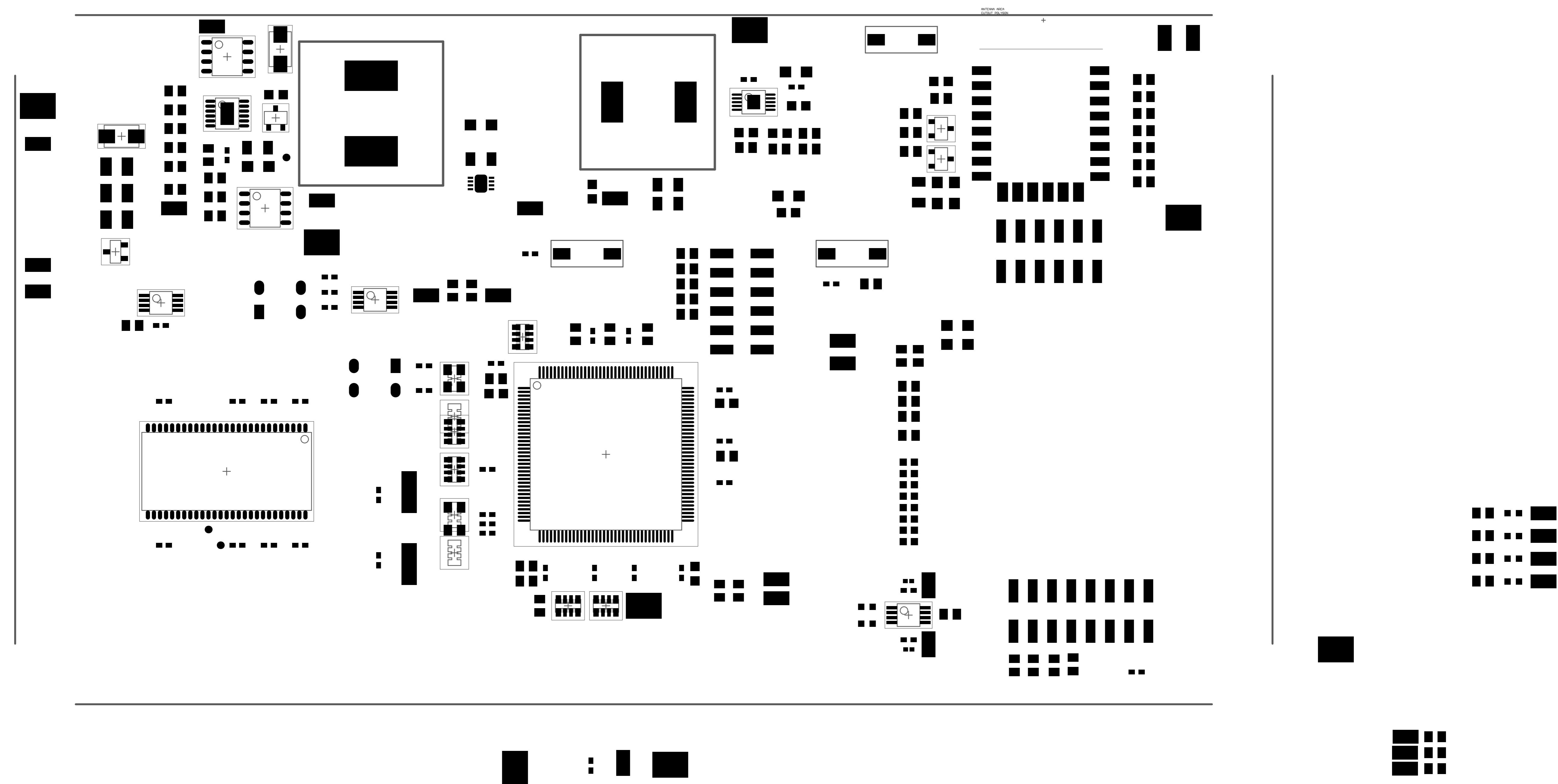


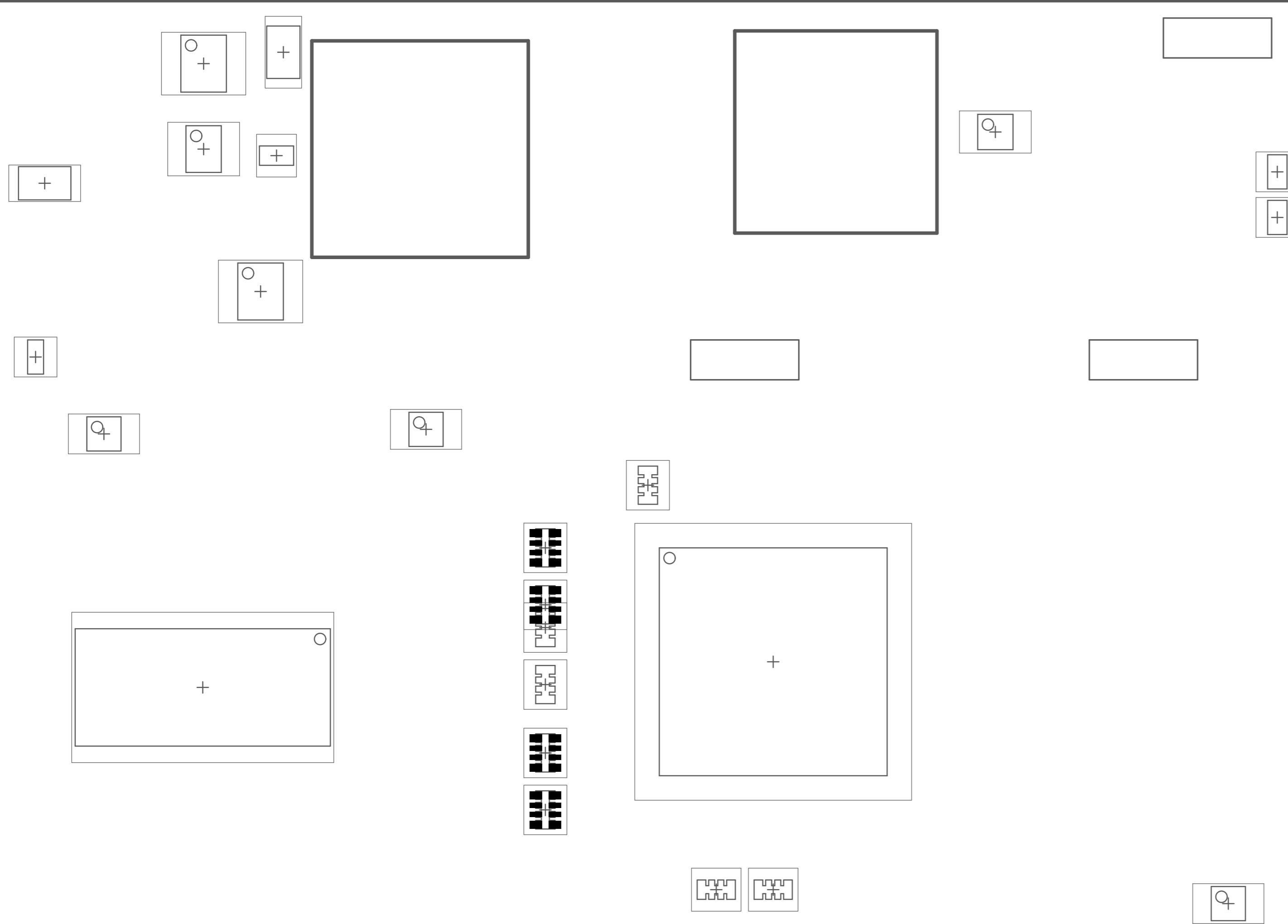
Board Stack Report

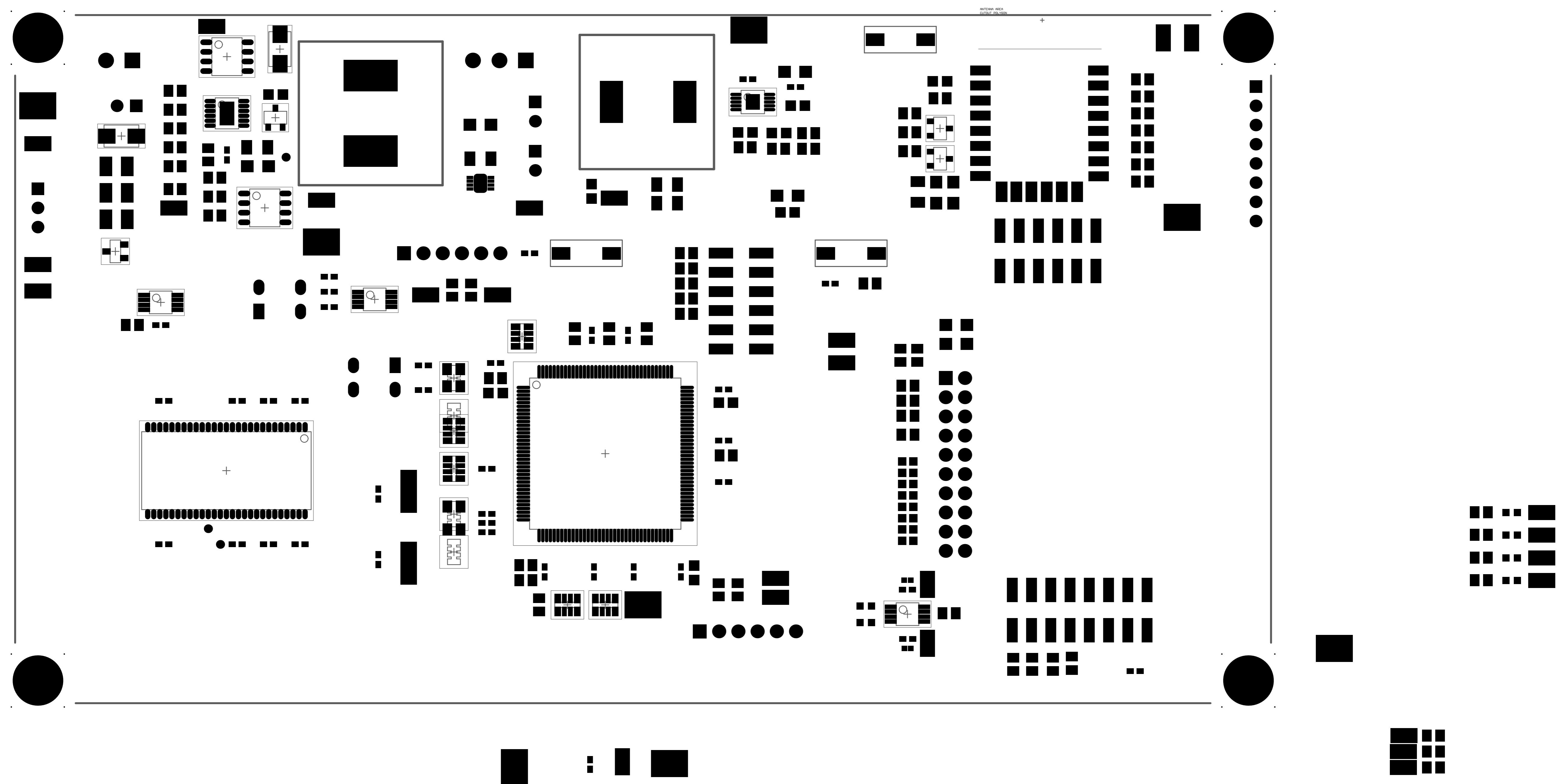
Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1	Top Paste				
2	Top Overlay				
3	Top Solder	Solder Resist		0.40mil	3.5
4	Top Layer	Copper		1.37mil	
5	Dielectric 1	2x2116		9.80mil	4.2
6	Signal Layer 2	Copper		1.37mil	
7	Dielectric 4			40.00mil	4.2
8	Signal Layer 1	Copper		1.37mil	
9	Dielectric 3	2x2116		9.80mil	4.2
10	Bottom Layer	Copper		1.37mil	
11	Bottom Solder	Solder Resist		0.40mil	3.5
12	Bottom Overlay				
13	Bottom Paste				
Height : 65.88mil					

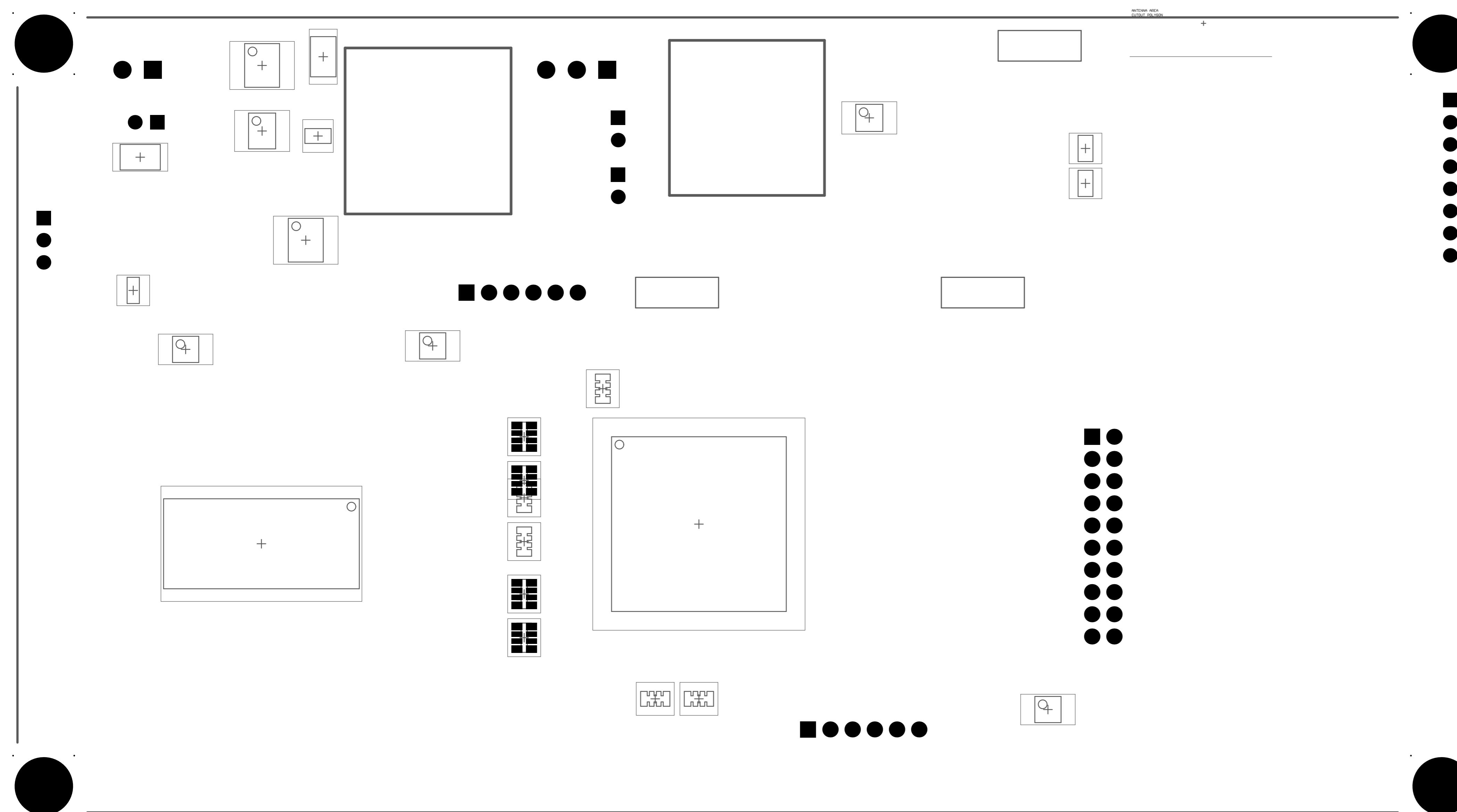


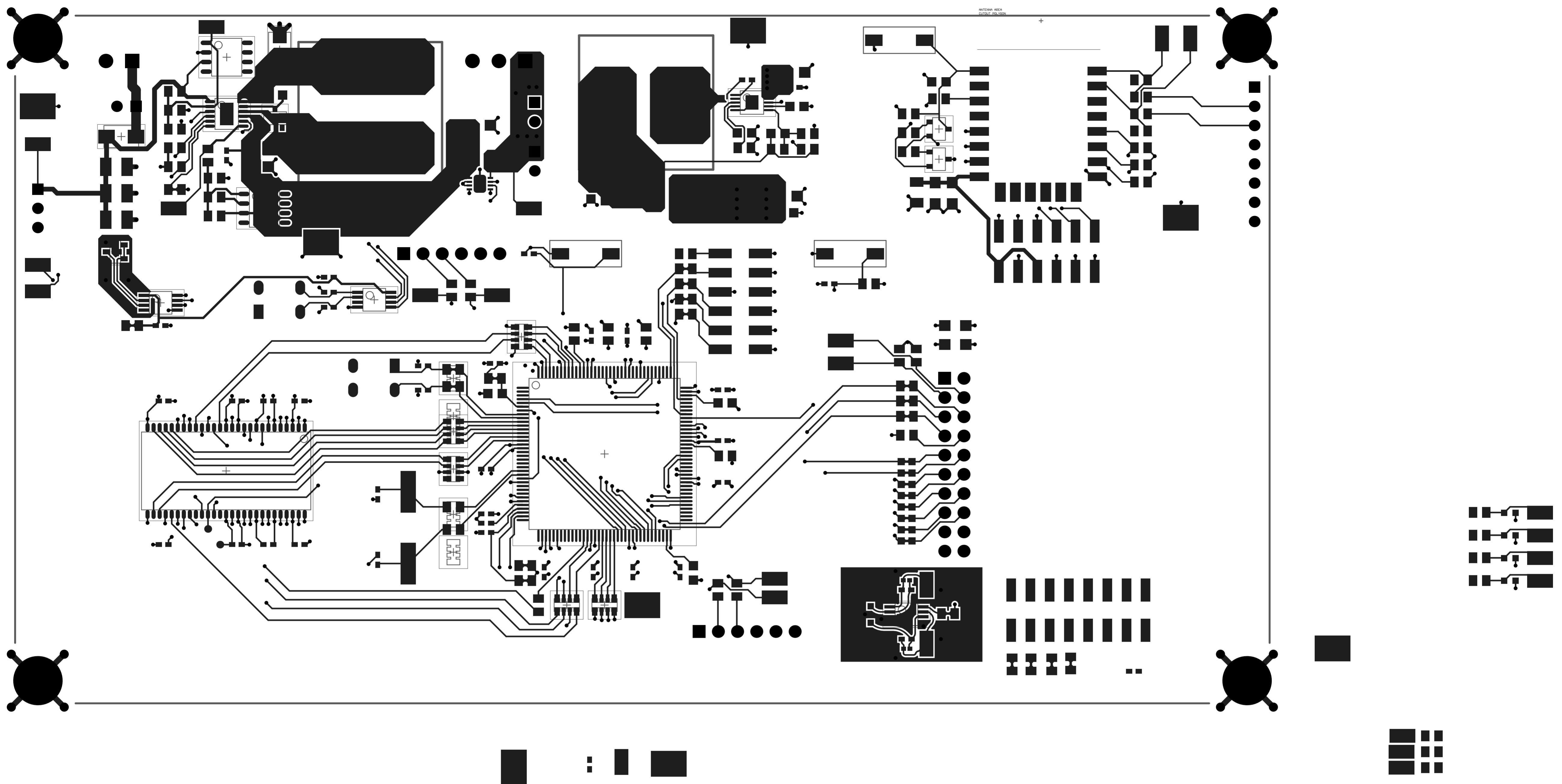


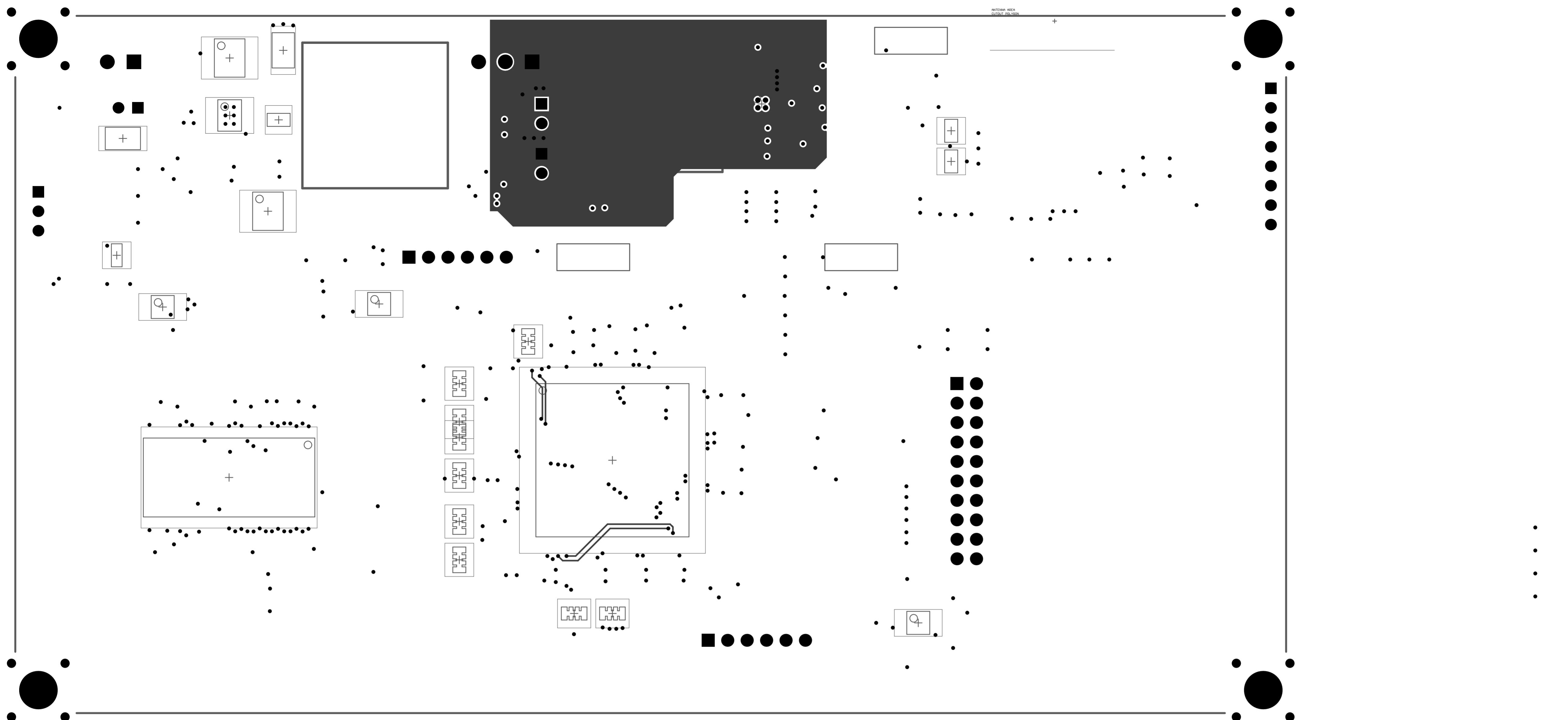


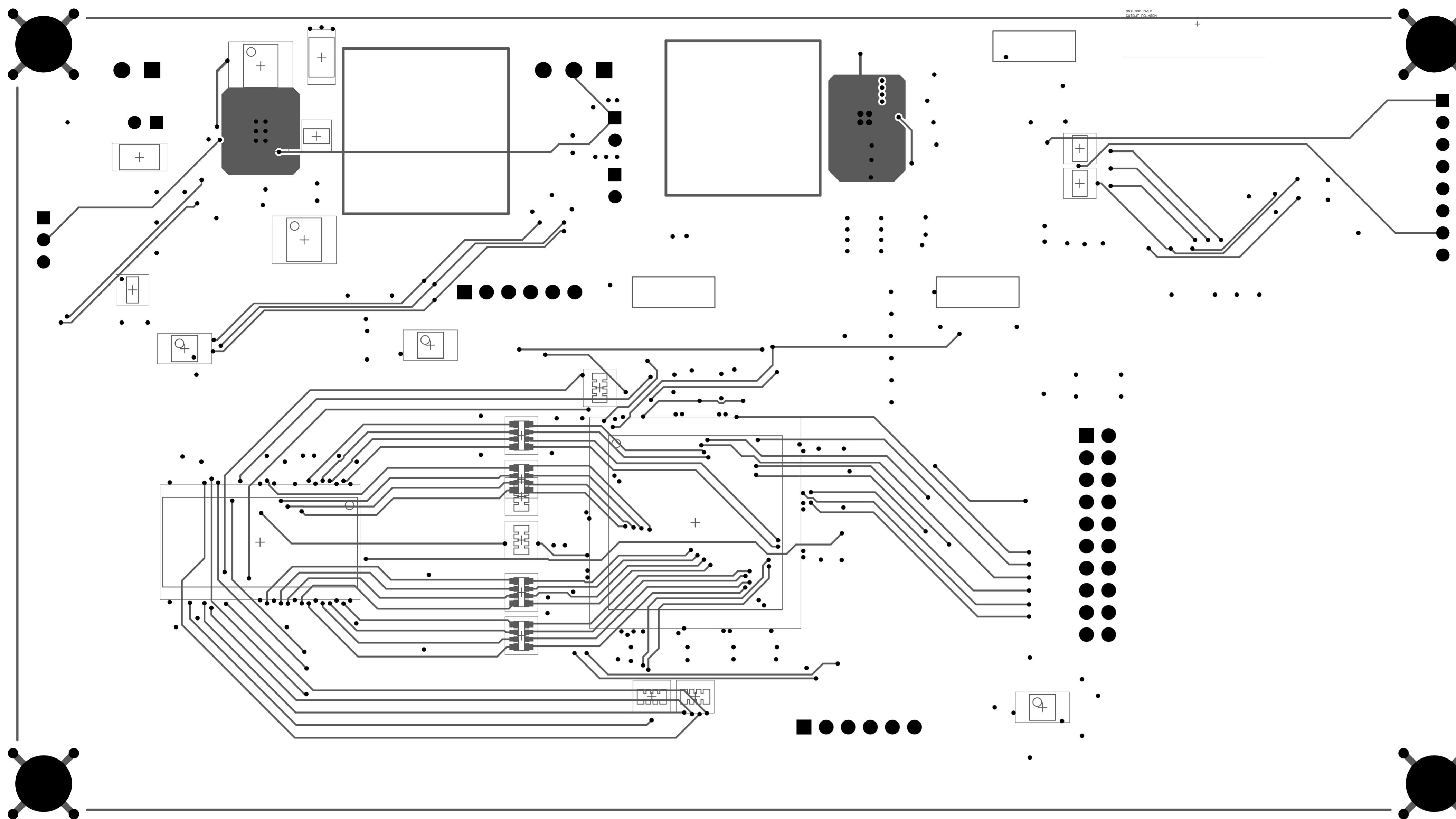


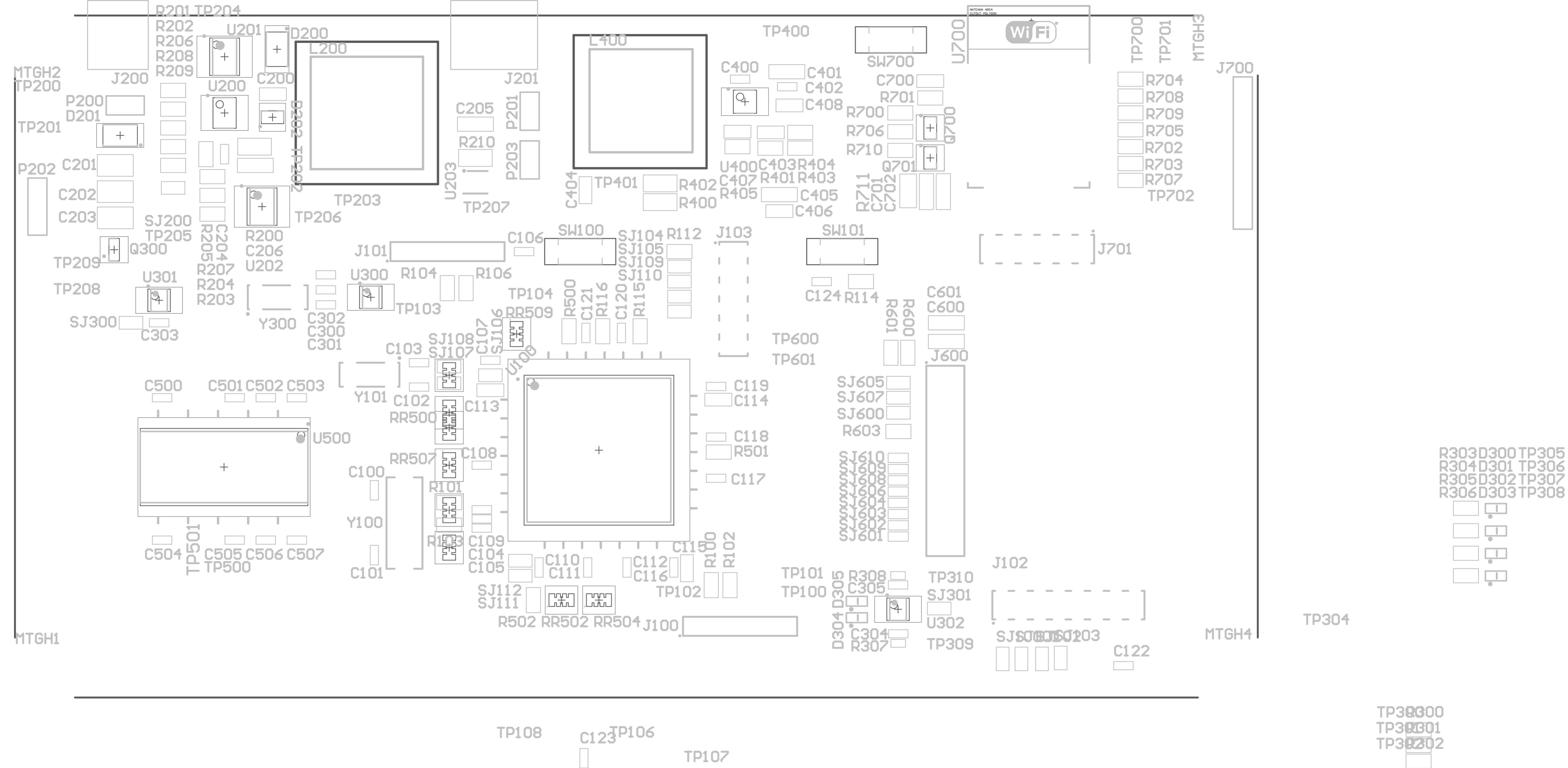












TP3QG00
TP3QG01
TP3QG02

